

# SOT1345-1

plastic thin fine-pitch ball grid array package; 50 balls

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	TFBGA50
<b>Package type industry code</b>	TFBGA50
<b>Package style descriptive code</b>	TFBGA (thin fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-195
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	17-7-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	4.9	-	5	5.1	mm
A	seated height	0.9	-	1	1.15	mm
A <sub>2</sub>	package height	0.75	-	0.8	0.9	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	50	-	



2. Package outline

TFBGA50: plastic thin fine-pitch ball grid array package; 50 balls; SOT1345-1

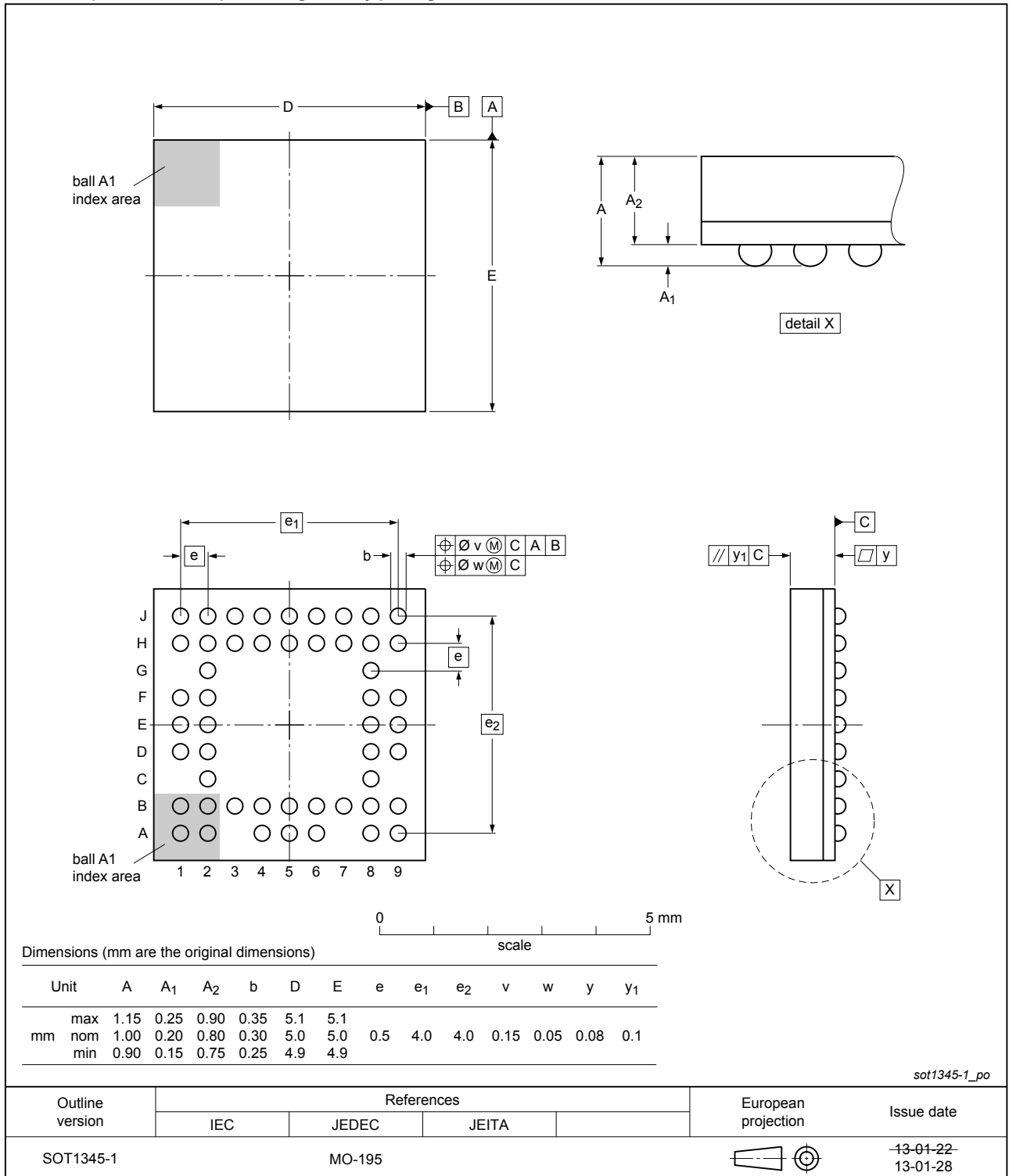
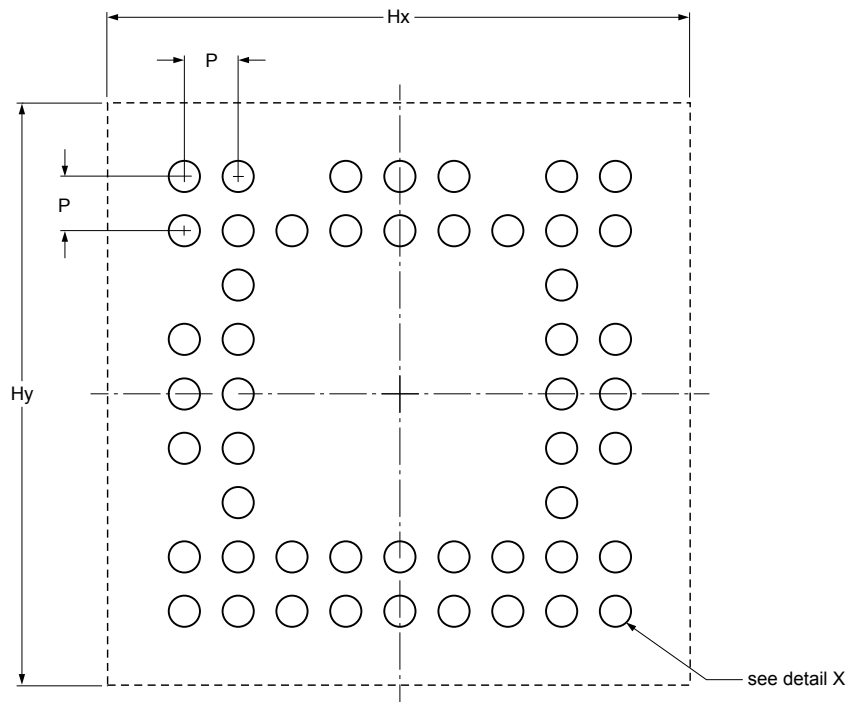


Fig. 1. Package outline TFBGA50 (SOT1345-1)




### 3. Soldering

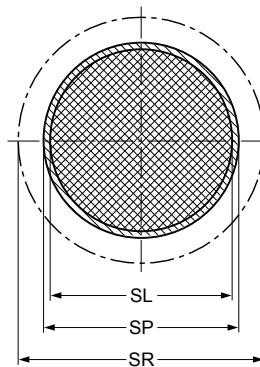
Footprint information for reflow soldering of TFBGA50 package

SOT1345-1



recommend stencil thickness: 0.1 mm

-  solder land (SL)
-  solder paste deposit (SP)
-  solder land plus solder paste
- · — · — solder resist opening (SR)
- - - - - occupied area



detail X

Dimensions in mm

P	SL	SP	SR	Hx	Hy
0.5	0.28	0.3	0.38	5.4	5.4

Issue date ~~14-07-31~~  
14-08-01

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Fig. 2. Reflow soldering footprint for TFBGA50 (SOT1345-1)

## 4. Legal information

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